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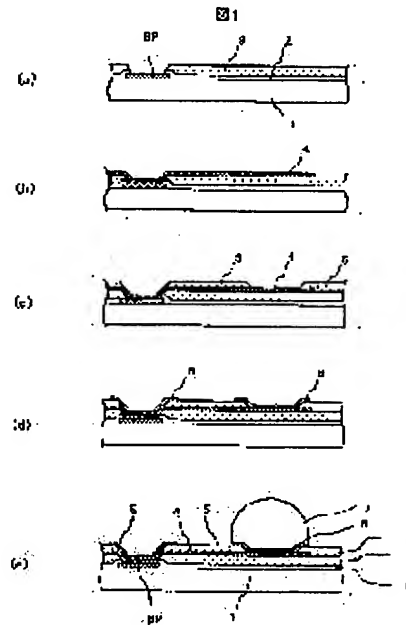
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(54) PATTERN FORMING METHOD AND MANUFACTURING METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To reduce the mask cost and to increase the productivity of many kinds of high-performance semiconductor devices in small quantities according to customer's usages.

SOLUTION: A semiconductor integrated circuit device is manufactured by using an inexpensive exposing device which uses a mercury lamp as its light source and a photomask which uses organic photosensitive resin as a substantial shading material for a process of forming a bonding pad and rearranged wires.



LEGAL STATUS

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